

**TEST STRUCTURE EMBEDDED IN A SHIPPING AND HANDLING
COVER FOR INTEGRATED CIRCUIT SOCKETS AND METHOD FOR
TESTING INTEGRATED CIRCUIT SOCKETS AND CIRCUIT
ASSEMBLIES UTILIZING SAME**

Abstract

A device for enabling testing of electrical paths through a circuit
5 assembly is presented. The device may include a test facilitating shipping
and handling cover for a socket of the circuit assembly. The test facilitating
shipping and handling cover may have a conductive layer for capacitively
coupling to an array of pins in the socket during testing. A method for testing
continuity of electrical paths through a circuit assembly is presented. In the
10 method, one or more nodes of the circuit assembly are stimulated, contacts
of a socket on the circuit assembly are capacitively coupled with a
conductive layer of a shipping and handling cover mated with the socket,
and an electrical characteristic is measured by a tester coupled to the
shipping and handling cover to determine continuity of electrical paths
15 through the circuit assembly.

Fig. 13